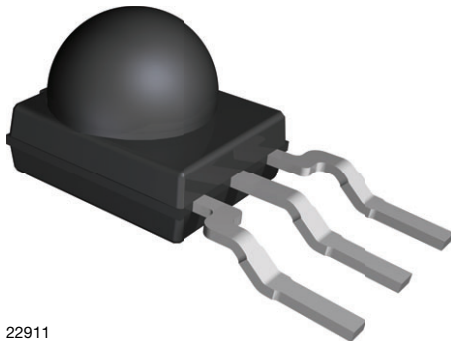


IR Receiver Modules for Remote Control Systems



22911

LINKS TO ADDITIONAL RESOURCES



Bends and Cuts

DESCRIPTION

The TSOP13...DF1P series devices are the latest generation miniaturized IR receiver modules for infrared remote control systems. This series provides improvements in sensitivity to remote control signals in dark ambient as well as in sensitivity in the presence of optical disturbances e.g. from CFLs. The robustness against spurious pulses originating from Wi-Fi signals has been enhanced.

The devices contain a PIN diode and a preamplifier assembled on a lead frame. The epoxy package contains an IR filter. The demodulated output signal can be directly connected to a microprocessor for decoding.

The TSOP131..DF1P, TSOP133..DF1P, and TSOP135..DF1P series devices are designed to receive short burst codes (6 or more carrier cycles per burst). The third digit designates the AGC level (AGC1, AGC3, or AGC5) and the last two digits designate the band-pass frequency (see table below). The higher the AGC, the better noise is suppressed, but the lower the code compatibility. AGC1 provides basic noise suppression, AGC3 provides enhanced noise suppression and AGC5 provides maximized noise suppression. Generally, we advise to select the highest AGC that satisfactorily receives the desired remote code.

These components have not been qualified to automotive specifications.

FEATURES

- Improved dark sensitivity
- Improved immunity against optical noise
- Improved immunity against Wi-Fi noise
- Low supply current
- Photo detector and preamplifier in one package
- Internal filter for PCM frequency
- Supply voltage: 2.5 V to 5.5 V
- Insensitive to supply voltage ripple and noise
- Material categorization: for definitions of compliance please see www.vishay.com/doc?99912



MECHANICAL DATA

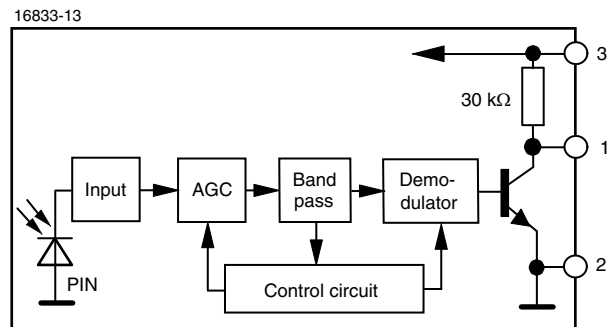
Pinning for TSOP13...DF1P:

1 = OUT, 2 = GND, 3 = V_S

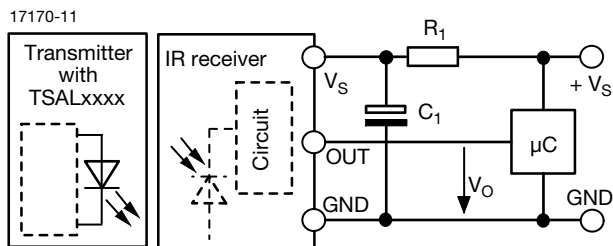
ORDERING CODE

TSOP13...DF1P - 1100 pieces in tape and reel

BLOCK DIAGRAM



APPLICATION CIRCUIT



R_1 and C_1 recommended to reduce supply ripple for $V_S < 2.8$ V



PARTS TABLE					
AGC		BASIC NOISE SUPPRESSION (AGC1)	ENHANCED NOISE SUPPRESSION (AGC3)	MAXIMIZED NOISE SUPPRESSION (AGC5)	
Carrier frequency	30 kHz	TSOP13130DF1P	TSOP13330DF1P	TSOP13530DF1P	
	33 kHz	TSOP13133DF1P	TSOP13333DF1P	TSOP13533DF1P	
	36 kHz	TSOP13136DF1P	TSOP13336DF1P ⁽¹⁾	TSOP13536DF1P	
	38 kHz	TSOP13138DF1P	TSOP13338DF1P ⁽²⁾⁽⁴⁾	TSOP13538DF1P	
	40 kHz	TSOP13140DF1P	TSOP13340DF1P	TSOP13540DF1P	
	56 kHz	TSOP13156DF1P	TSOP13356DF1P ⁽³⁾	TSOP13556DF1P	
Package		Minimold			
Pinning		1 = OUT, 2 = GND, 3 = V _S			
Dimensions (mm)		5.4 W x 6.35 H x 4.9 D			
Mounting		SMD			
Application		Remote control			
Best choice for		⁽¹⁾ RCMM ⁽²⁾ RECS-80 Code ⁽³⁾ r-map ⁽⁴⁾ XMP-1, XMP-2			
Special options		<ul style="list-style-type: none"> Narrow optical filter: www.vishay.com/doc?81590 Wide optical filter: www.vishay.com/doc?82726 			

Note

- 30 kHz and 33 kHz only available on written request

ABSOLUTE MAXIMUM RATINGS				
PARAMETER	TEST CONDITION	SYMBOL	VALUE	UNIT
Supply voltage		V _S	-0.3 to +6	V
Supply current		I _S	3	mA
Output voltage		V _O	-0.3 to (V _S + 0.3)	V
Output current		I _O	5	mA
Junction temperature		T _j	100	°C
Storage temperature range		T _{stg}	-25 to +85	°C
Operating temperature range		T _{amb}	-25 to +85	°C
Power consumption	T _{amb} ≤ 85 °C	P _{tot}	10	mW
Soldering temperature	t ≤ 10 s, 1 mm from case	T _{sd}	260	°C

Note

- Stresses beyond those listed under “Absolute Maximum Ratings” may cause permanent damage to the device. This is a stress rating only and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of this specification is not implied. Exposure to absolute maximum rating conditions for extended periods may affect the device reliability

ELECTRICAL AND OPTICAL CHARACTERISTICS (T _{amb} = 25 °C, unless otherwise specified)						
PARAMETER	TEST CONDITION	SYMBOL	MIN.	TYP.	MAX.	UNIT
Supply current	E _v = 0, V _S = 3.3 V	I _{SD}	0.55	0.7	0.9	mA
	E _v = 40 klx, sunlight	I _{SH}	-	0.8	-	mA
Supply voltage		V _S	2.5	-	5.5	V
Transmission distance	E _v = 0, test signal see Fig. 1, IR diode TSAL6200, I _F = 50 mA	d	-	30	-	m
Output voltage low	I _{OSL} = 0.5 mA, E _e = 0.7 mW/m ² , test signal see Fig. 1	V _{OSL}	-	-	100	mV
Minimum irradiance	Pulse width tolerance: t _{pi} - 3.0/f ₀ < t _{po} < t _{pi} + 3.5/f ₀ , test signal see Fig. 1	E _{e min.}	-	0.08	0.15	mW/m ²
Maximum irradiance	t _{pi} - 3.0/f ₀ < t _{po} < t _{pi} + 3.5/f ₀ , test signal see Fig. 1	E _{e max.}	30	-	-	W/m ²
Maximum long burst irradiance (AGC3, AGC5)	t _{pi} - 3.0/f ₀ < t _{po} < t _{pi} + 3.5/f ₀ , test signal see Fig. 1, dark ambient, burst length > 30 cycles	E _{e max.}	0.5	-	-	W/m ²
Directivity	Angle of half transmission distance	φ _{1/2}	-	± 45	-	°

TYPICAL CHARACTERISTICS ($T_{amb} = 25\text{ }^{\circ}\text{C}$, unless otherwise specified)

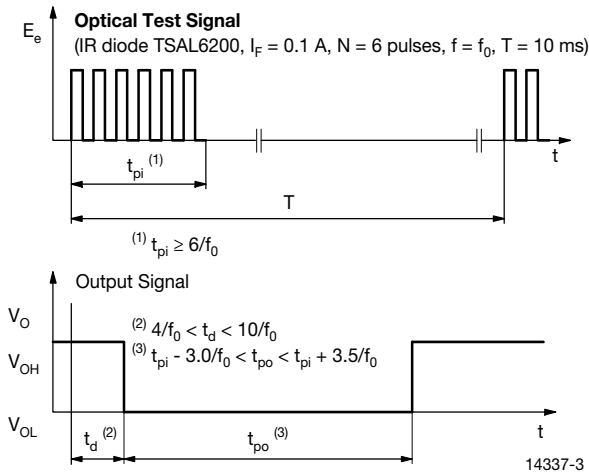


Fig. 1 - Output Delay and Pulse-Width

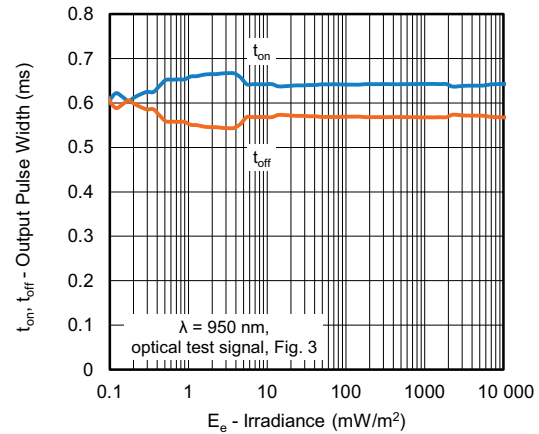


Fig. 4 - Pulse-Width vs. Irradiance in Dark Ambient

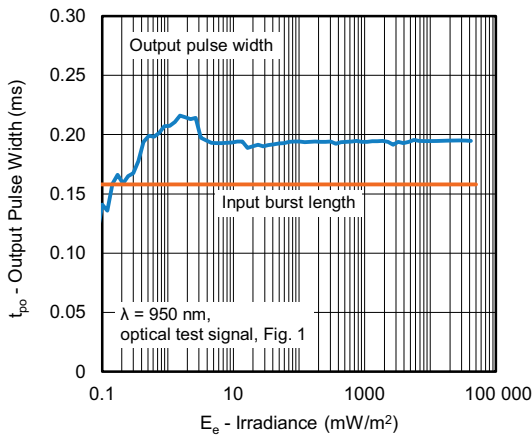


Fig. 2 - Pulse-Width vs. Irradiance in Dark Ambient

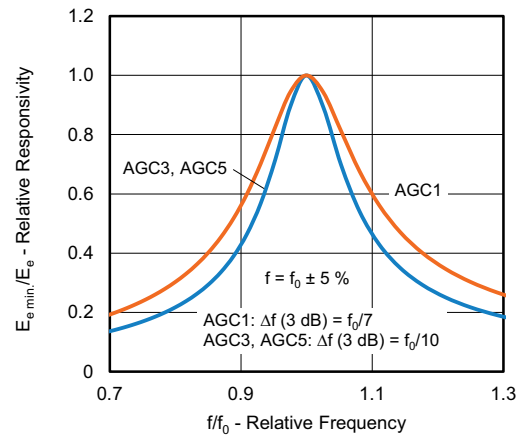


Fig. 5 - Frequency Dependence of Responsivity

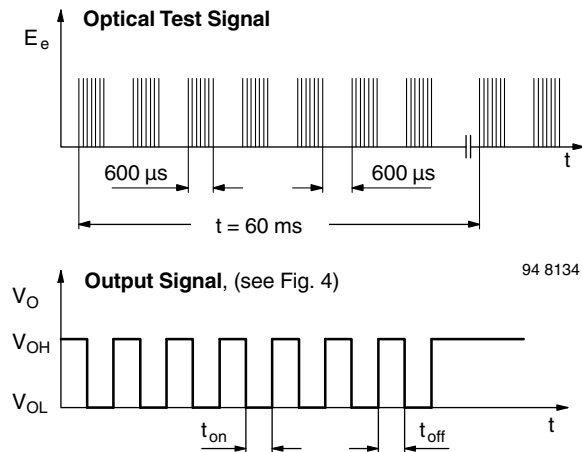


Fig. 3 - Test Signal

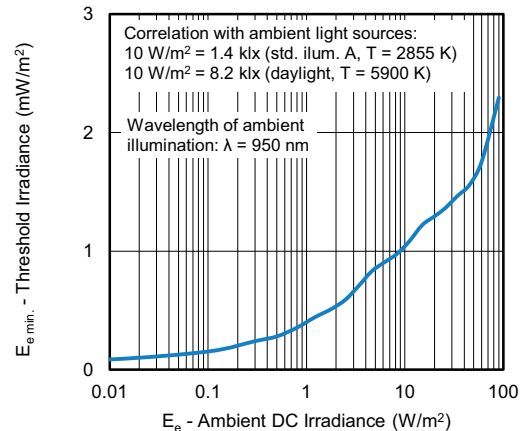


Fig. 6 - Sensitivity in Bright Ambient

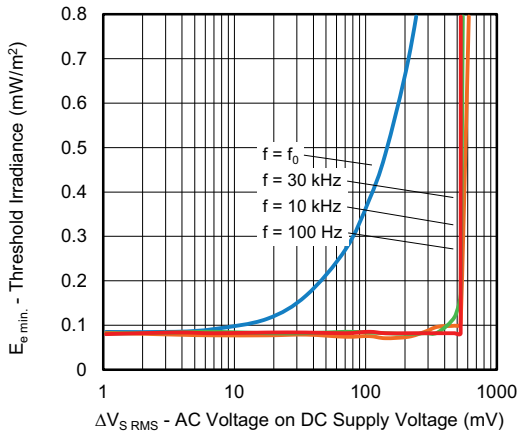


Fig. 7 - Sensitivity vs. Supply Voltage Disturbances



Fig. 10 - Relative Spectral Sensitivity vs. Wavelength

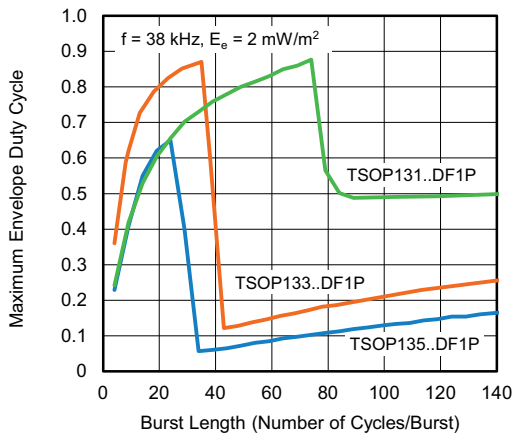


Fig. 8 - Max. Envelope Duty Cycle vs. Burst Length



Fig. 11 - Directivity

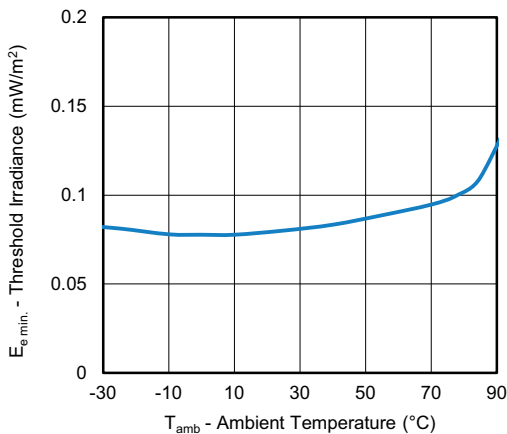


Fig. 9 - Sensitivity vs. Ambient Temperature

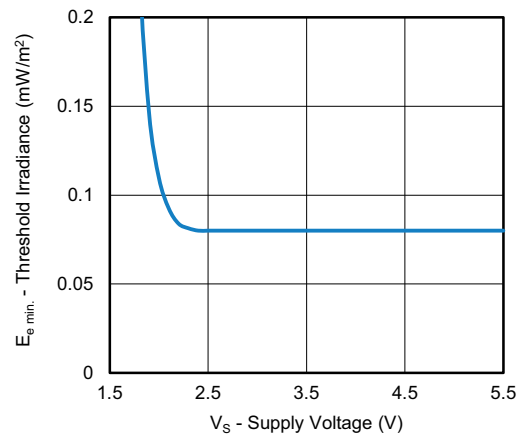


Fig. 12 - Sensitivity vs. Supply Voltage

SUITABLE DATA FORMAT

This series is designed to suppress spurious output pulses due to noise or disturbance signals. The devices can distinguish data signals from noise due to differences in frequency, burst length, and envelope duty cycle. The data signal should be close to the device's band-pass center frequency (e.g. 38 kHz) and fulfill the conditions in the table below.

When a data signal presented to the device in the presence of a disturbance, the sensitivity of the receiver is automatically reduced by the AGC to insure that no spurious pulses are present at the receiver's output. Some examples which are suppressed are:

- DC light (e.g. from tungsten bulbs sunlight)
- Continuous signals at any frequency
- Strongly or weakly modulated patterns from fluorescent lamps with electronic ballasts (see Fig. 13 or Fig. 14).
- 2.4 GHz and 5 GHz Wi-Fi

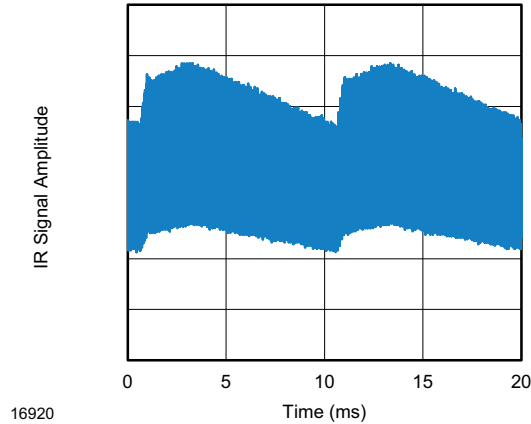


Fig. 13 - IR Disturbance from Fluorescent Lamp With Low Modulation

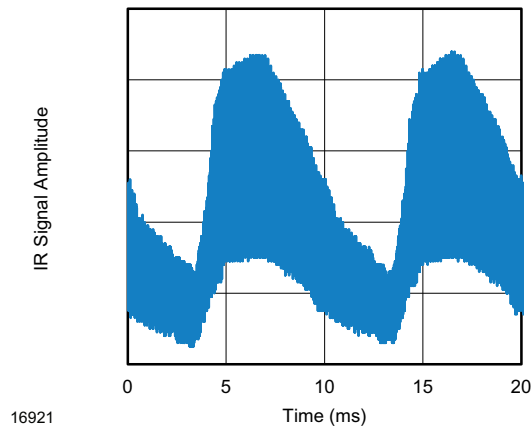


Fig. 14 - IR Disturbance from Fluorescent Lamp With High Modulation

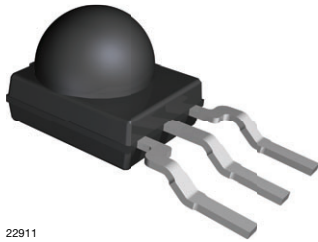
	TSOP131..DF1P	TSOP133..DF1P	TSOP135..DF1P
Minimum burst length	6 cycles/burst	6 cycles/burst	6 cycles/burst
After each burst of length A gap time is required of	6 to 70 cycles ≥ 10 cycles	6 to 35 cycles ≥ 10 cycles	6 to 24 cycles ≥ 10 cycles
For bursts greater than a minimum gap time in the data stream is needed of	70 cycles > 1 x burst length	35 cycles > 6 x burst length	24 cycles > 25 ms
Maximum number of continuous short bursts/second	1800	2800	1800
RCMM code	Yes	Preferred	Yes
XMP-1 code	Yes	Preferred	Yes
r-map code	Yes	Preferred	Yes
Suppression of interference from fluorescent lamps	Fig. 13	Fig. 13 and Fig. 14	Fig. 13 and Fig. 14

Note

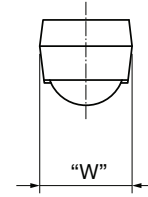
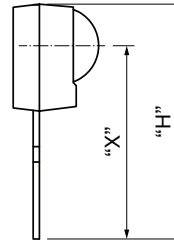
- For data formats with long bursts (more than 10 carrier cycles) please see the datasheet for TSOP132..DF1P, TSOP134..DF1P, TSOP136..DF1P



BENT LEADS: H = 11.4 mm, W = 5.4 mm, X = 8.85 mm



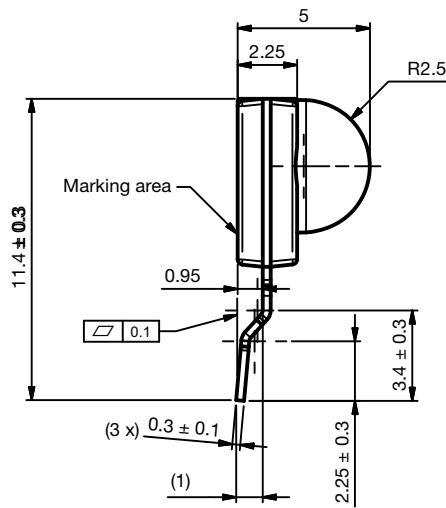
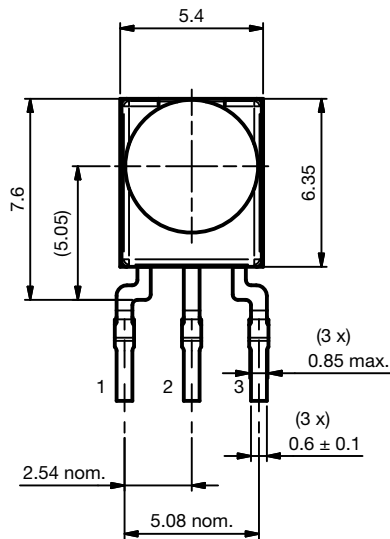
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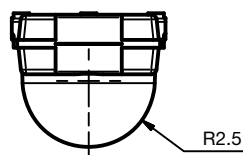
20258

NAME	LENS AXIS (X)	VIEW	TYPE	HEIGHT (H)	WIDTH (W)	DEPTH (D)
DF1P	8.85	-	Bend	11.4	5.4	-

MECHANICAL DIMENSIONS in millimeters

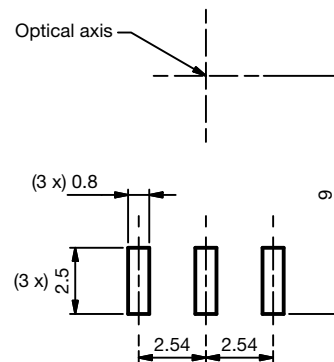


Not indicated tolerances ± 0.2



Technical drawings according to DIN specification

Proposed pad layout from component side (for reference only)



Drawing-No.: 6.550-5343.01-4
Issue: 2; 02.07.19



ASSEMBLY INSTRUCTIONS

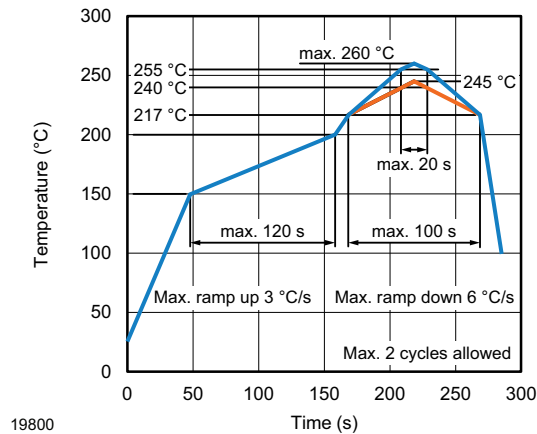
Reflow Soldering

- Reflow soldering must be done within 72 h while stored under a max. temperature of 30 °C, 60 % RH after opening the dry pack envelope
- Set the furnace temperatures for pre-heating and heating in accordance with the reflow temperature profile as shown in the diagram. Exercise extreme care to keep the maximum temperature below 260 °C. The temperature shown in the profile means the temperature at the device surface. Since there is a temperature difference between the component and the circuit board, it should be verified that the temperature of the device is accurately being measured
- Handling after reflow should be done only after the work surface has been cooled off

Manual Soldering

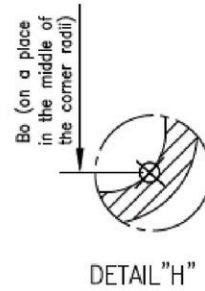
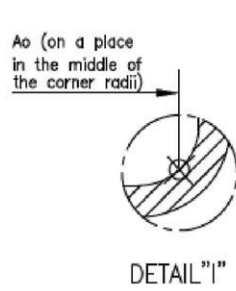
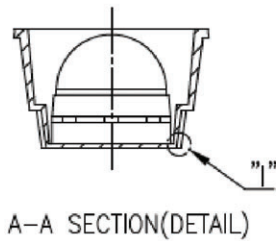
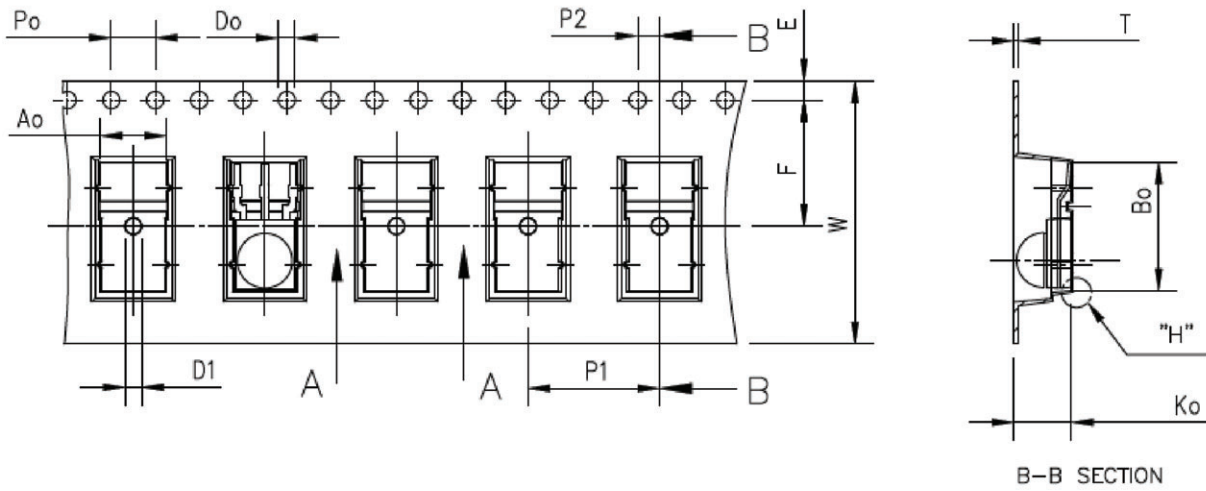
- Use a soldering iron of 25 W or less. Adjust the temperature of the soldering iron below 300 °C
- Finish soldering within 3 s
- Handle products only after the temperature has cooled off

VISHAY LEAD (Pb)-FREE REFLOW SOLDER PROFILE





PACKAGING DIMENSIONS in millimeters

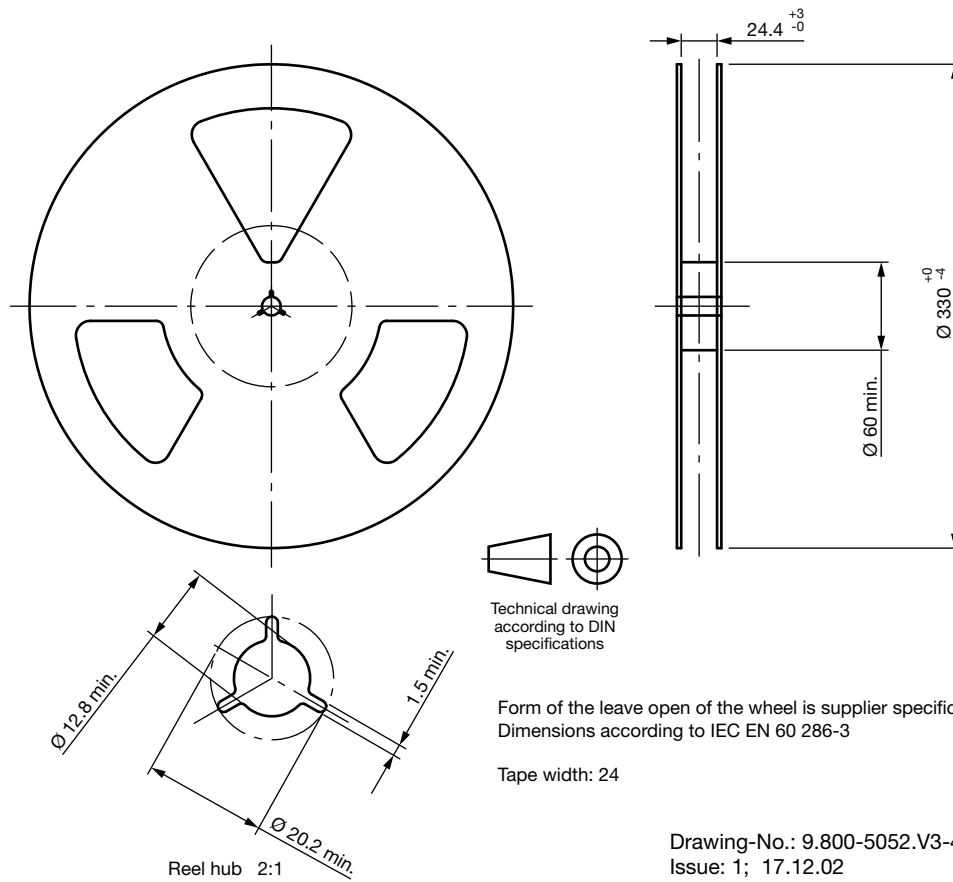


Drawing-No.: 9.700-5399.01-4
Issue: 2; 29.06.18

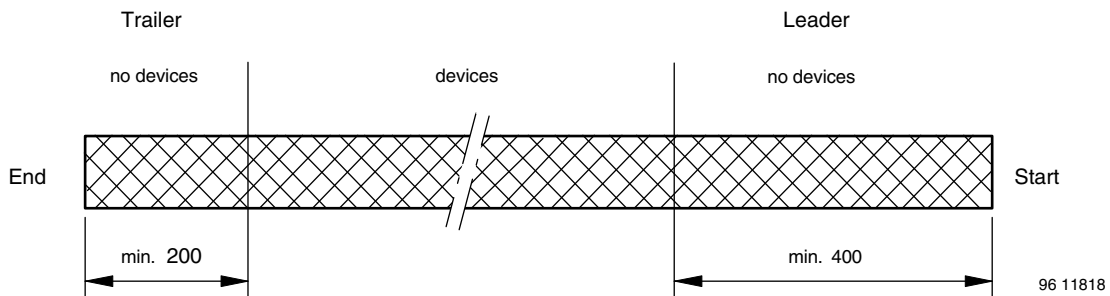
Item	A_0	B_0	K_0	P_0	P_1	P_2	T
Dimensions	6.08 ± 0.10	11.75 ± 0.10	5.25 ± 0.10	4.0 ± 0.10	12.0 ± 0.10	2.0 ± 0.10	0.40 ± 0.05
Item	E	F	D_0	D_1	W	$10P_0$	
Dimensions	1.75 ± 0.10	11.50 ± 0.10	1.55 ± 0.05	1.5 min.	$24.0 +0.30 / -0.10$	40.0 ± 0.20	



REEL DIMENSIONS in millimeters



LEADER AND TRAILER DIMENSIONS in millimeters



COVER TAPE PEEL STRENGTH

According to DIN EN 60286-3

0.1 N to 1.3 N

300 mm/min. ± 10 mm/min.

165° to 180° peel angle



ORDERING INFORMATION



Note

- d = “digit”, please consult the list of available series on the previous page to create a valid part number

Example: TSOP13538DF1P

PACKAGING QUANTITY

- 1100 pieces per reel
- 1 reel per box

LABEL

Standard bar code labels for finished goods

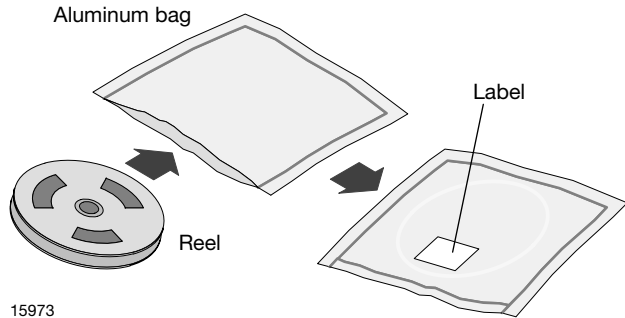
The standard bar code labels are product labels and used for identification of goods. The finished goods are packed in final packing area. The standard packing units are labeled with standard bar code labels before transported as finished goods to warehouses. The labels are on each packing unit and contain Vishay Semiconductor GmbH specific data.

VISHAY SEMICONDUCTOR GmbH STANDARD BAR CODE PRODUCT LABEL (finished goods)		
PLAIN WRITING	ABBREVIATION	LENGTH
Item-description	-	18
Item-number	INO	8
Selection-code	SEL	3
LOT-/serial-number	BATCH	10
Data-code	COD	3 (YWW)
Plant-code	PTC	2
Quantity	QTY	8
Accepted by	ACC	-
Packed by	PCK	-
Mixed code indicator	MIXED CODE	-
Origin	xxxxxxx+	Company logo
LONG BAR CODE TOP	TYPE	LENGTH
Item-number	N	8
Plant-code	N	2
Sequence-number	X	3
Quantity	N	8
Total length	-	21
SHORT BAR CODE BOTTOM	TYPE	LENGTH
Selection-code	X	3
Data-code	N	3
Batch-number	X	10
Filter	-	1
Total length	-	17



DRY PACKING

The reel is packed in an anti-humidity bag to protect the devices from absorbing moisture during transportation and storage.



FINAL PACKING

The sealed reel is packed into a cardboard box. A secondary cardboard box is used for shipping purposes.

RECOMMENDED METHOD OF STORAGE

Dry box storage is recommended as soon as the aluminum bag has been opened to prevent moisture absorption. The following conditions should be observed, if dry boxes are not available:

- Storage temperature 10 °C to 30 °C
- Storage humidity ≤ 60 % RH max.

After more than 72 h under these conditions moisture content will be too high for reflow soldering.

In case of moisture absorption, the devices will recover to the former condition by drying under the following condition:

- 192 h at 40 °C + 5 °C / - 0 °C and < 5 % RH (dry air / nitrogen) or
- 96 h at 60 °C + 5 °C and < 5 % RH for all device containers or
- 24 h at 125 °C + 5 °C not suitable for reel or tubes.

An EIA JEDEC® standard J-STD-020 level 4 label is included on all dry bags.

ESD PRECAUTION

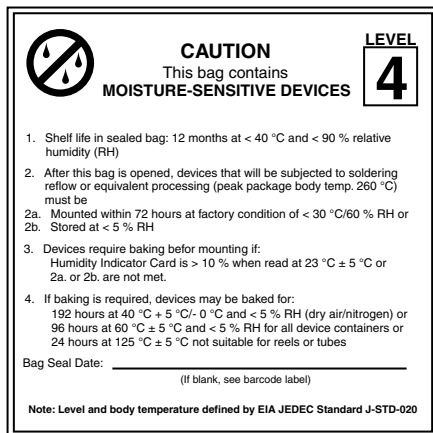
Proper storage and handling procedures should be followed to prevent ESD damage to the devices especially when they are removed from the antistatic shielding bag. Electrostatic sensitive devices warning labels are on the packaging.

VISHAY SEMICONDUCTORS STANDARD BAR CODE LABELS

The Vishay Semiconductors standard bar code labels are printed at final packing areas. The labels are on each packing unit and contain Vishay Semiconductors specific data.



22645



22522

EIA JEDEC standard J-STD-020 level 4 label is included on all dry bags



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